

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	502517	(substrate carrier board ((printed wiring circuit) adj3 board)) same (bond (bond adj pad) terminal pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/09 23:31
L2	267494	1 same (no connection connected connect)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/09 23:34
L3	190616	1 same (no with connection connected connect)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/09 23:34
L4	191614	1 same ((without no none) with connection connected connect)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/09 23:35
L5	15973	1 same ((without no none) with (connection connected connect))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/09 23:41
L6	238926	5 sme (inactive)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/09 23:36
L7	115	5 same (inactive)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/09 23:36
L8	0	257/class	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/09 23:41

L9	3615	5 and (bump ball)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/09 23:43
L10	14506	5 and (terminal electrode bump ball)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/09 23:44
L11	6071	10 and 1 and (microelectronic ic (integrated adj circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/09 23:55
L12	134	(redistribution redistribute redistributed redistributed) and 11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/09 23:47
L13	240	11 and (dummy)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/09 23:55
L14	233	13 not 12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/09 23:55

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L2	267494	1 same (no connection connected connect)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/10 10:42
L3	190616	1 same (no with connection connected connect)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/10 10:42
L4	191614	1 same ((without no none) with connection connected connect)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/10 10:42
L5	903	4 same (inactive)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/10 10:46
L6	169234	4 and (terminal electrode bump ball)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/10 10:43
L7	56119	6 and 1 and (microelectronic ic (integrated adj circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/10 10:43
L8	909	(redistribution redistribute redistributed redistributed) and 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/10 10:49

L9	40	8 and (dummy)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/10 10:46
L10	903	5 same (inactive)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/10 10:46
L11	83961	5and (dummy)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/10 10:46
L12	26	5 and (dummy)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/10 10:48
L13	3573	6 and (dummy)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/10 10:48
L14	71	(redistribution redistribute redistributed redistributed) and 13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/10 10:49